

ABSTRACT

A circuit board with protrusions at desired locations on a wiring pattern that on the surface of the board. The protrusions are made of the same conductive material used in the wiring pattern, and formed unitarily and simultaneously with the wiring pattern. Conductive material is filled into grooves having different depths and formed on a film. The filled conductive material is transferred onto the board, and then fired. Thus the circuit board is manufactured. Semiconductor devices and general-purpose components are mounted on the circuit board, whereby a semiconductor device can be manufactured with high reliability and at an inexpensive cost.